CRMKGL1008A

N-Channel 100V, 6.0mΩ Typ. Power MOSFET

Description

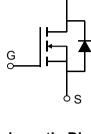
Features

• 100V, 95A

$$R_{DS(ON)}$$
 Typ = 6.0m Ω @ V_{GS} = 10V

$$R_{DS(ON)}$$
 Typ = 8.5m Ω @ V_{GS} = 4.5V

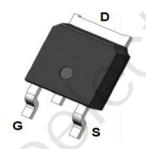
- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





Application

- Load Switch
- PWM Application
- Power Management





Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKGL1008A	CRMKGL1008A	TO-252-3L	TAPING	13"	2500	25000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		100	V
V _{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	95	Α
I _D		T _C = 100°C	57	А
I _{DM}	Pulsed Drain Current (1)		380	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		132	mJ
P_{D}	Power Dissipation	T _C = 25°C	125	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		1	°C/W
T_{J}, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.4	2.0	2.6	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10V, I_D = 30A$	-	6.0	7.8	mΩ
		$V_{GS} = 4.5V, I_D = 30A$	-	8.5	11	mΩ
Dynamic	Characteristics					
C_{iss}	Input Capacitance			2400	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 25V,$ f = 1MHz	X - \	1320	-	pF
C_{rss}	Reverse Transfer Capacitance	1 - 1101112		45	-	pF
Q_g	Total Gate Charge		U -	45	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 50V, I_{D} = 20A$	-	9	-	nC
Q_gd	Gate Drain("Miller") Charge	VDS - 00 V, ID - 20/1	-	7	-	nC
Switchin	g Characteristics					
$t_{d(on)}$	Turn-On DelayTime	.rO	-	12	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 50V$	-	15	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	I_D = 20A, R_{GEN} = 3Ω	-	33	-	ns
t_f	Turn-Off Fall Time		-	20	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	95	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	380	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 20A, di/dt = 100A/us	-	55	-	ns
Qrr	Body Diode Reverse Recovery Charge	1 _F - 20A, 41/41 - 100A/48	-	77	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =50V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =23A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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Test Circuit

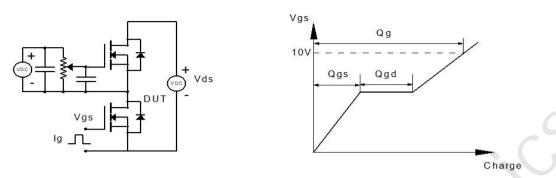


Figure 1: Gate Charge Test Circuit & Waveform

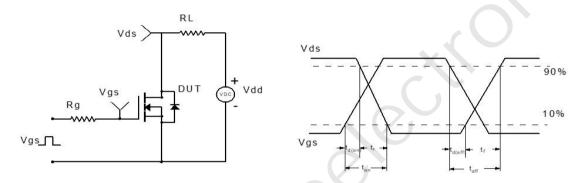


Figure 2: Resistive Switching Test Circuit & Waveform

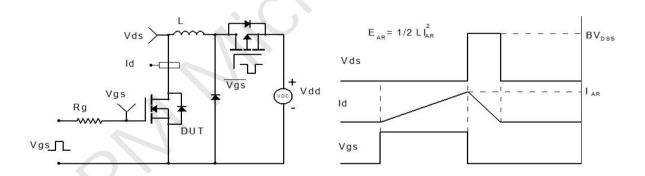


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

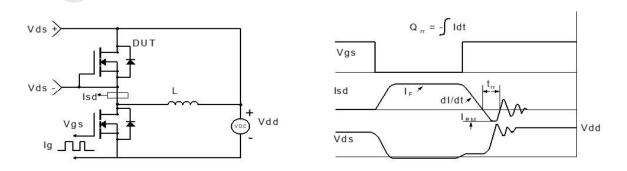
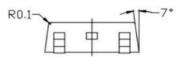


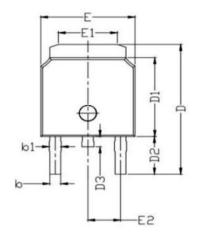
Figure 4: Diode Recovery Test Circuit & Waveform

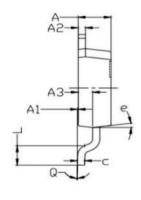
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Package Mechanical Data(TO-252-3L)







COMMON DIMENSION(MM)					
PKG	TO-252-3L				
Symbot	MIN	MIN MON			
Α	2.250	2.300	2.400		
A1	0.010	0.060	0.150		
A2	0.500	0.508	0.550		
A3	0.960	1.010	1.060		
b	0.740	0.760	0.800		
b1	0.880	0.900	0.950		
С	0.500	0.508	0.550		
D	9.800	10.025	10.350		
D1	6.050	6.100	6.180		
D2	2.850	2.900	2.950		
D3	0.700	0.800	2.900		
E	6.550	6.600	6.700		
E1	4.050	4.130	4.200		
E2	2.250	2.286	2.300		
L	1.400	1.500	1.600		
е	7.000				
Q	0°	2°	5°		

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Contact information

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